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(71)Applicant : KYOCERA CORP

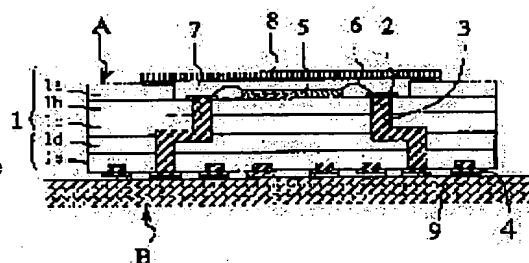
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(72)Inventor : KAWAI SHINYA

(54) GLASS COMPOSITION, GLASS SINTERED COMPACT AND WIRING BOARD OBTAINED BY USING THE SINTERED COMPACT**(57)Abstract:**

PROBLEM TO BE SOLVED: To provide a wiring board which can be burned at $\leq 1,000^{\circ}\text{C}$, and in which a wiring layer containing low resistance metal can simultaneously be formed by burning, and which has a thermal expansion coefficient suitable for the packaging of GaAs chips, and a low Young's modulus, and ensures the long term reliability of connecting parts.

SOLUTION: In the wiring board provided with a wiring layer 2 containing low resistance metal provided on the surface and/or the inside of an insulation board 1, as the insulation board 1, a glass sintered compact is used which is obtained by molding glass powder containing, by weight, 10 to 40% SiO_2 , 1 to 30% Al_2O_3 , 10 to 40% BaO , 1 to 20% Y_2O_3 , 0 to 30% B_2O_3 , 0 to 25% ZnO , 0 to 20% of at least one kind selected from the group consisting of MgO , CaO and SrO , and 0 to 10% of at least one kind selected from the group consisting of ZrO_2 , SnO_2 and TiO_2 , and $\geq 90\%$ the total content of the above components, and thereafter performing burning thereto at $\leq 1,000^{\circ}\text{C}$.

**LEGAL STATUS**

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